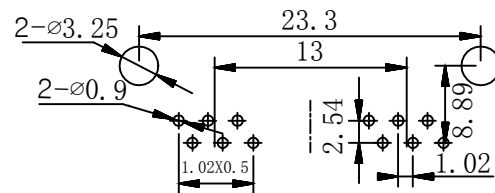
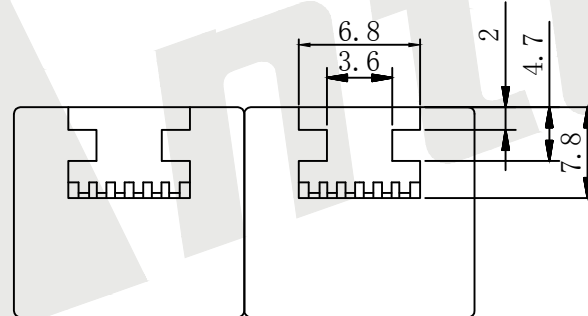
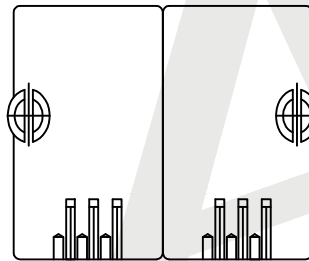
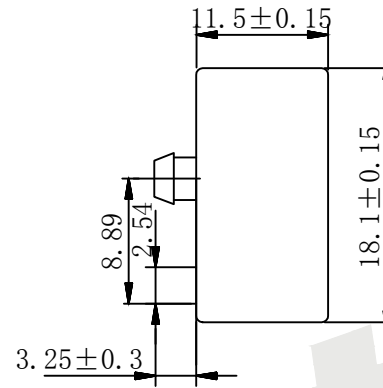
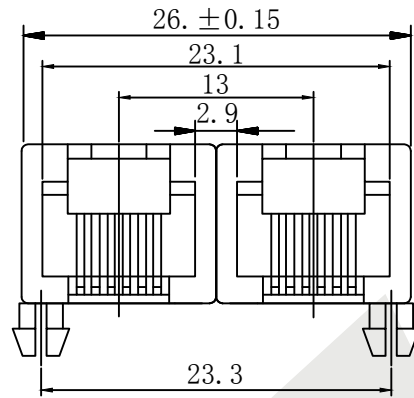


HSF



PC Board Layout
Component Side Shown

NOTES:

MATERIAL:

1. HOUSING MATERIAL: GLASS FILLED POYESTER UL94V-0.
 2. CONTACT MATERIAL: PHOSPHOR BRONZE $t=0.3\text{mm}$
 3. PLATING: SELECTING GOLD PLATING $1\mu\sim 50\mu$ OVER NICKEL IN CONTACT AREA. 150μ TIN PLATIN. OVER NICKEL IN SOLDER AREA
 4. SHIELD: 0.2mm THICKNESS COPPER WITH NICKEL PLATE
- ELECTRICAL
1. VOLTAGE RATING: 125VAC RMS
 2. CURRENT RATING: 1.5AMP
 3. CONTACT RESISTANCE: 30MILLIOHMS MAX
 4. INSULATION RESISTANCE 500MEGOHMS MIN @500V DC
 5. DIELECTRIC WITHSTANDING RESISTANCE : 1000V AC RMS 50Hz. 1MIN

MECHANICAL

1. DURRABILITY: 750 CYCLES MIN
2. PCB RETENTTON PRB-SOLDER: 1 LB MIN

REVIROMENTAL

1. STORAGE: -40°C TO 85°C
2. OPERATION: 0°C TO 70°C

Order code:

ATRJ5323 - 6P - 6C - X - A - B
① ② ③ ④ ⑤ ⑥

① SERIES NO:

② NUMBER OF POSITIONS (8P, 6P, 4P)

③ NUMBER OF CONTACTS (8C, 6C, 4C)

④ Contact Plating

- G0: Gold flash
- G1: 3U" Gold
- G2: 5U" Gold
- G3: 10U" Gold
- G4: 15U" Gold
- G5: 30U" Gold
- SN: Tin

⑤ Shield

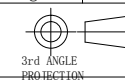
- A: W/O Shield
- B: Half Shield
- C: Shield W/Eml
- D: Shield W/O Eml

⑥ Ports

- A: 1X1P
- B: 1X2P
- C: 1X4P
- D: 1X5P
- E: 1X6P
- F: 1X8P

Unless Otherwise specified tolerance
X. ±0.35 X.XX: ±0.20
X.X: ±0.25 X.XXX: ±0.15

SCALE: As Shown UNIT: mm
DRAW Wu Sai DATE 22/03/2018
CHECK BobYang DATE 22/03/2018



Antenk® ANTENK ELECTRONICS CO., LTD
Http://www.antenk.com
E-mail:sales@antenk.com

TITLE: RJ11 Jack 6P6C, Side entry, 1X2Port, Full plastic

DRAWING NO: ATRJ5323-6P6C-X-A-B

PRODUCT NO: ATRJ5323-6P6C-X-A-B

REV	DESCRIPTION	DATE
1		
2		
3		
4		
5		